



Product Change Notification: MAAN-02DPIM838

Date:

08-Jun-2026

Product Category:

Memory

Notification Subject:

CCB 7235.002 and 6183.009 Final Notice: Qualification of MTAI as an additional assembly and final test site for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package.

Affected CPNs:

[MAAN-02DPIM838_Affected_CPN_06082026.pdf](#)

[MAAN-02DPIM838_Affected_CPN_06082026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly and final test site for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Final Test Site	Amkor Technology	Amkor Technology	Microchip Technology	Yes
Assembly Site				

	Philippine (P1/P2), INC. (ANAP)	Philippine (P1/P2), INC. (ANAP)	Thailand (HQ) (MTAI)	
Wire Material	PdCu	PdCu	CuPdAu	Yes
Die Attach Material	8290 (PFAS)	8290 (PFAS)	QMI519 (PFAS-free)	Yes
Molding Compound Material	G700A	G700A	G600V	Yes
Lead-Frame Material	C194	C194	CDA194	No
Lead-Frame Paddle Size	95 x 155 mils	95 x 155 mils	95 x 130 mils	Yes
DAP Surface Prep	PPF	PPF	Bare Cu	Yes
Lead Plating	NiPdAu	NiPdAu	Matte Tin	Yes
Lead Lock	No	No	Yes, locking hole	Yes
Packing Material/Method	See Pre and Post change for comparison.			Yes

* Note: C194, A194 or CDA194 Lead-frame materials are the same, it is just a MCHP internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity and on-time delivery performance by qualifying MTAI as an additional assembly and final test site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 July 2026 (date code: 2631)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					July 2026			
Work Week	23	24	25	26	27	28	29	30	31

Qual Report Availability		x							
Final PCN Issue Date		x							
Estimated Implementation Date									x

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 08, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MAAN-02DPIM838_Pre and Post Change_Summary.pdf
PFAS Elimination and Die Attach_Explanation.pdf
PCN_MAAN-02DPIM838 Qual Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

AT25M01-SSHM-T

AT25M01-SSHM-B



QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: MAAN-02DPIM838

Date:
June 05, 2026

Qualification of MTAI as an additional assembly and final test site for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package will qualify similarity (QBS).



MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly and final test site for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package. This is a qualification by similarity (QBS).
CCB No.	7877 (Qual Date: December 1, 2025) and 7235.002
CN	E000283997
QUAL ID	R2501232 Rev A
Bonding No.	BD-002568 Rev.01
MP CODE	66902YC3XS00
Part No.	25CSM01T-E/SM
<u>Lead Frame</u>	
Paddle size	140 x 160 mils
Material	CDA194
Surface	Bare Cu
Treatment	Roughened
Process	Stamped
Lead lock	No
Part number	10100840
Plating composition	Matte Tin
<u>Bond Wire</u>	
Wire	CuPdAu wire
<u>Die Attach Material</u>	
Epoxy	QMI519
<u>Mold Compound</u>	
Mold compound	G600V
<u>Package</u>	
Type	8L SOIJ
Package size	.208



MICROCHIP

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI262201620.000	U08D926044450.000	25355MH
MTAI262300197.000	U08D926044450.000	25367A2
MTAI262201827.000	U08D926044450.000	253579C

Result

☒ Pass ☐ Fail ☐ _____

8L SOIJ (.208) assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT Bake 150°C, 24 hrs. System: CHINEE 85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243	JESD22-A113 JIP/ IPC/JEDEC J-STD-020E	693(0)	0/693	Pass	Good Devices
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +85°C and 125°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>3.00 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.6 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504hrs. System: TPS Bake Oven	JESD22- A103		135		45 units / lot
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PT		135(0)	0/135	Pass	
Bond Strength Data Assembly	Wire Pull (>3.00 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC- Q100-001	30(0) Bonds	0/30	Pass	



QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: MAAN-02DPIM838

Date:
June 05, 2026

Qualification of ASSH and MTAI as an additional final test sites for AT25080B-XHL-B, AT25080B-XHL-T, AT25160B-XHL-B, AT25160B-XHL-T catalog part numbers (CPN) and qualification of ASSH as an additional final test site for selected 25LC080D, 25LC160C, 25LC160D, 25AA080C, 25AA080D, 25AA160C, 25AA160D, and 25LC080C devices families in 8L TSSOP (4.4mm) package, together with qualification of MTAI as an additional final test site for AT25080B-SSHL-T, AT25080B-SSHL-B, AT25160B-SSHL-B, and AT25160B-SSHL-T catalog part numbers (CPN) available in 8L SOIC (3.90mm) package. Qualification of MTAI as an additional assembly and final test site for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package will qualify similarity (QBS).



Process Qualification Report

Purpose: Qualification of ASSH and MTAI as an additional final test sites for AT25080B-XHL-B, AT25080B-XHL-T, AT25160B-XHL-B, AT25160B-XHL-T catalog part numbers (CPN) and qualification of ASSH as an additional final test site for selected 25LC080D, 25LC160C, 25LC160D, 25AA080C, 25AA080D, 25AA160C, 25AA160D, and 25LC080C devices families in 8L TSSOP (4.4mm) package, together with qualification of MTAI as an additional final test site for AT25080B-SSHL-T, AT25080B-SSHL-B, AT25160B-SSHL-B, and AT25160B-SSHL-T catalog part numbers (CPN) available in 8L SOIC (3.90mm) package. Qualification of MTAI as an additional assembly and final test site for AT25M01-SSHM-T and AT25M01-SSHM-B catalog part numbers (CPN) available in 8L SOIC (.150in) package will qualify similarity (QBS).

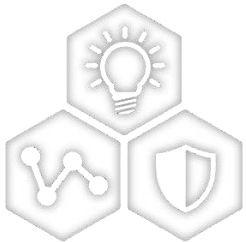
CCB No.: 6183.007 (Qual Date: March 05, 2026) and 6183.009

Test Name	Test Condition	Result
Test Correlation	Correlation on production ATE in strip form at each site and compare results between the two sites > Build and test (> 3000 pcs.) for checkout in ASSH > Compare test yields from checkout in MTAI with ANAP historic yields	Passed

CCB 7235.002 and 6183.009 Pre and Post Change Summary PCN #: MAAN-02DPIM838



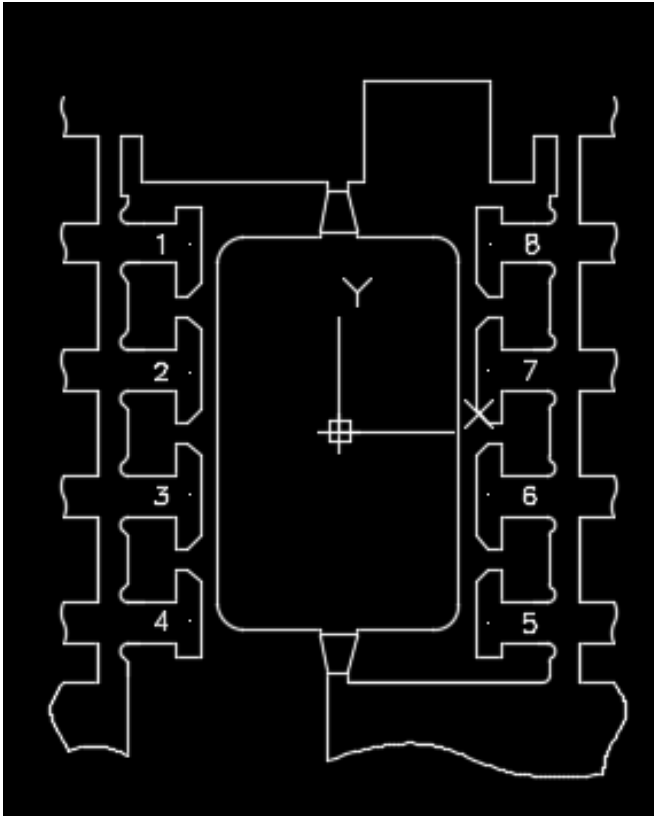
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SMART | CONNECTED | SECURE

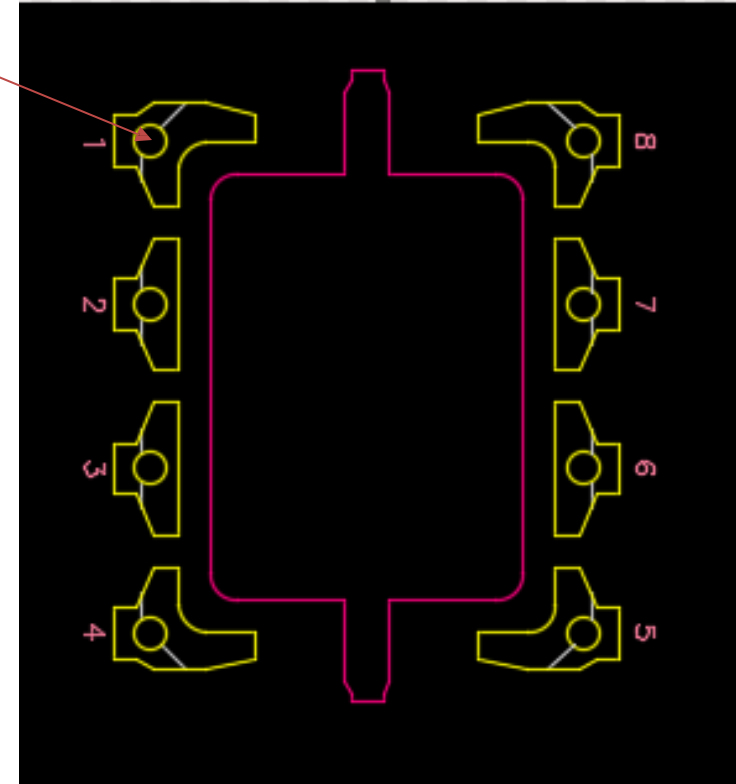
Lead-frame Comparison

ANAP



MTAI

Lead lock



Note 1: Mold compound materials fills the leadlock hole, which provides improved protection against moisture penetration along the edge of the leads (pins) of the package.

Note 2: C194, A194 or CDA194 Lead-frame materials are the same, it is just a MCHP internal labelling difference.

Note 3: Not to scale.

Pre and post change - 8L SOIC (.150in) -TUBE

ANAP

MTAI

MCHP PIN	SUPPLIER PIN	TUBE COLOUR	PRINT COLOUR
20100607	TBD	CLEAR	BLUE

REV.	CN NO.	DESCRIPTION	PROPOSED BY
U	00000104	UPDATE PRINTING ON TUBE AND NOTE SHEET 5	RATTANALAK S.
V	00000104	UPDATE NOTE ITEM 4 AND 5 SHEET 5	RATTANALAK S.
W	00000104	UPDATE TUBE PART NUMBER IN SHEET 5	JATURAPAT J.
X	00000104	ADD INTERNAL TUBE IN SHEET 5	RATTANALAK S.
Y	00000104	UPDATE INTERNAL TUBE PART NUMBER SHEET 6	RATTANALAK S.
		UPDATE TUBE MCHP PIN 20100607 SHEET 7	RATTANALAK S.
		ADD MCHP PIN 20100607 AND NOTE ITEM 6 IN SHEET 6	RATTANALAK S.

K07-042-3 (FROM MTAI)

Location	Tube Length (inch)	Tube Color	Units per Tube	Tubes per Bag
ANAP	20.450 +/-0.05 inch	Clear	100	100
MTAI	20.50 +/-0.05 inch	Clear	100	100

Packing Method Non-Dry Pack - Tube

ANAP



SSB

BAG WIDTH	BAG LENGTH
304mm	635mm



Barcode Label

ESD Sticker (4x4)

Carton	Dimension W x L x H (cm)	Number of Bag/carton
M02-010	12.9x56.5x8	1

MTAI



SSB

BAG WIDTH	BAG LENGTH
160mm	650mm



ESD logo

Label



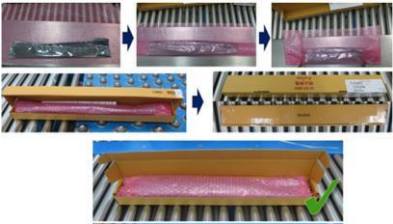
ANTI STATIC TAPE

MSL-1 (No inner box)

Carton for product in tubes media (MSL -1)

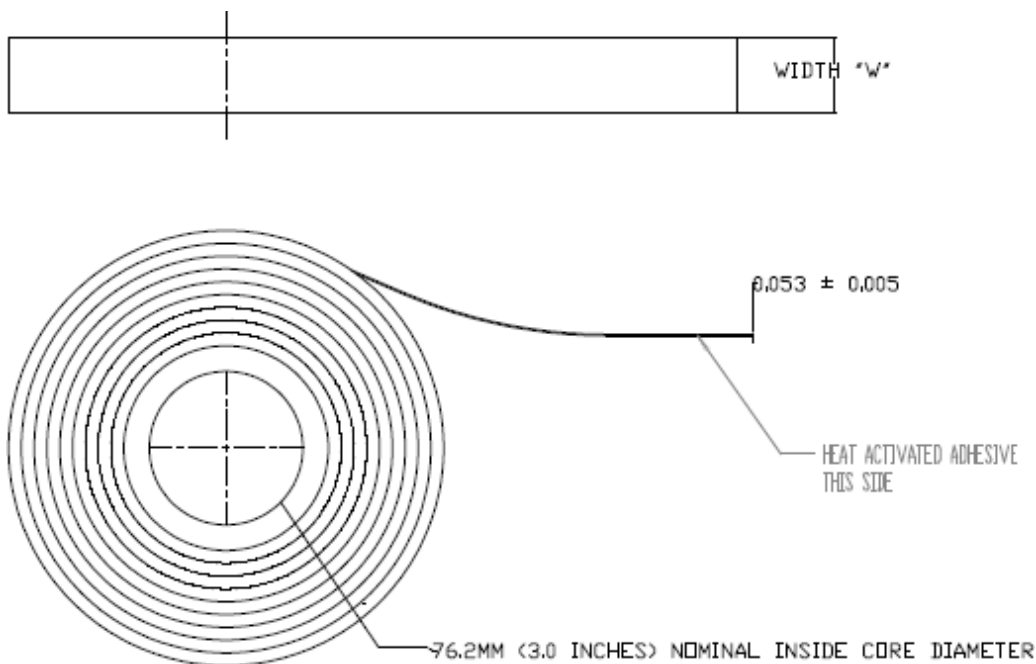
M01-025 (C1)	15x64x5.5	1
M01-026 (C2)	15x64x10	2
M01-027 (C3)	15x64x14	3
M01-028 (C4)	28x63x11	4
M01-029 (C6)	28x63x15.5	6
M01-030 (C8)	28x63x20	8

Example:

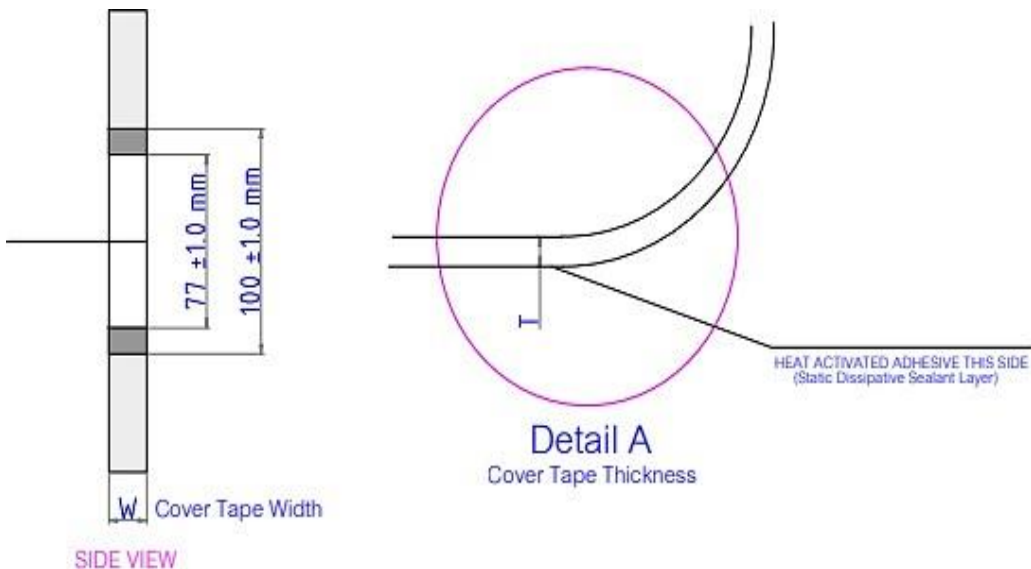


Pre and post change - 8L SOIC Cover Tape

ANAP



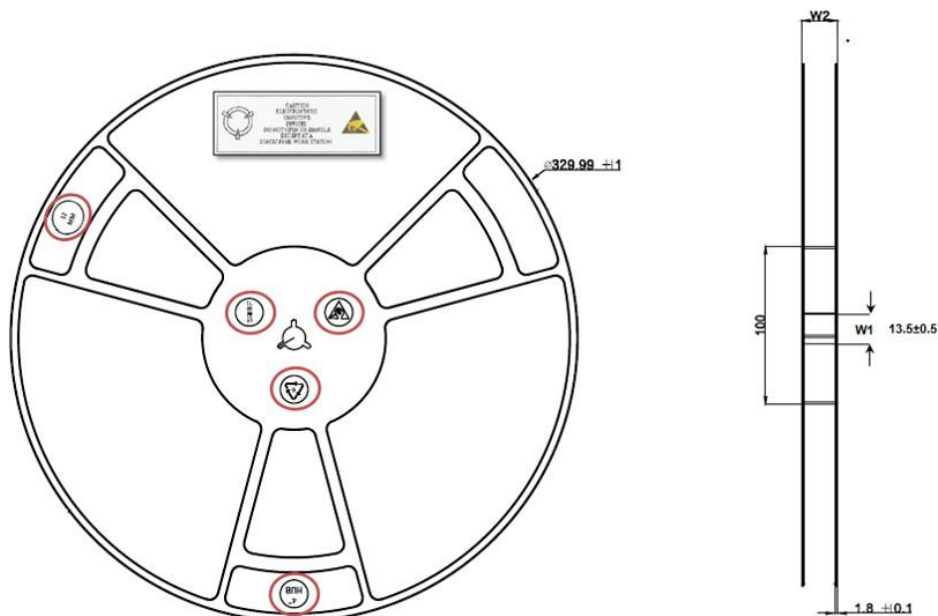
MTAI



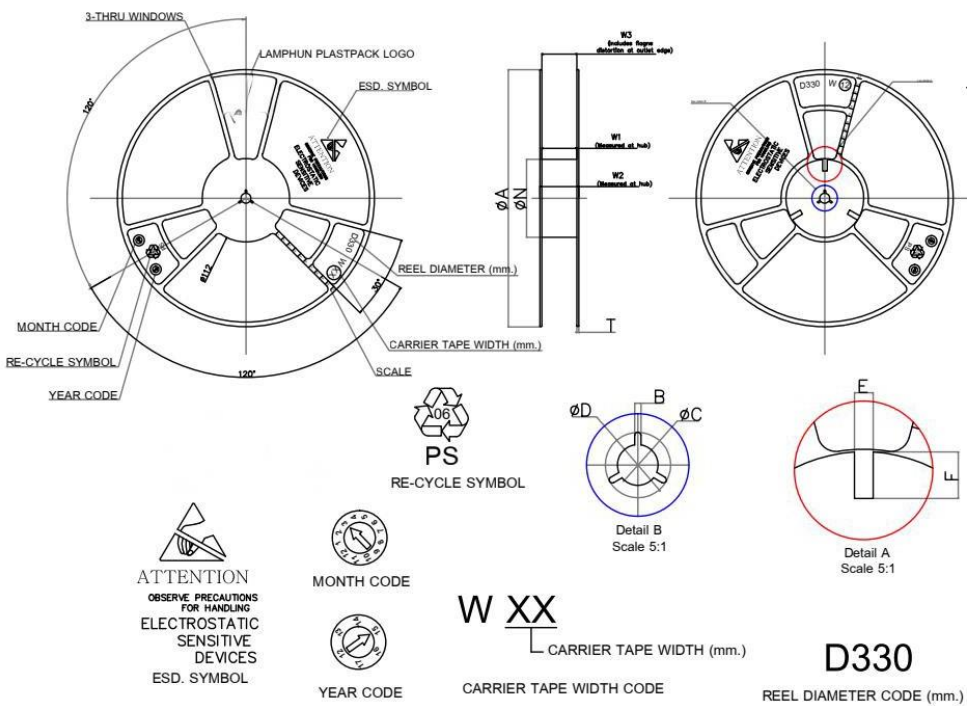
Plant	Width W (mm)	Thickness (mm)	Color	Sealing Methodology
ANAP	9.20 +/-0.10	0.053 +/- 0.005	Clear	Heat Seal
MTAI	9.05 +0.05/-0.010	0.050 +/- 0.010	Clear	Heat Seal

Pre and post change - 8L SOIC Plastic Reel

ANAP



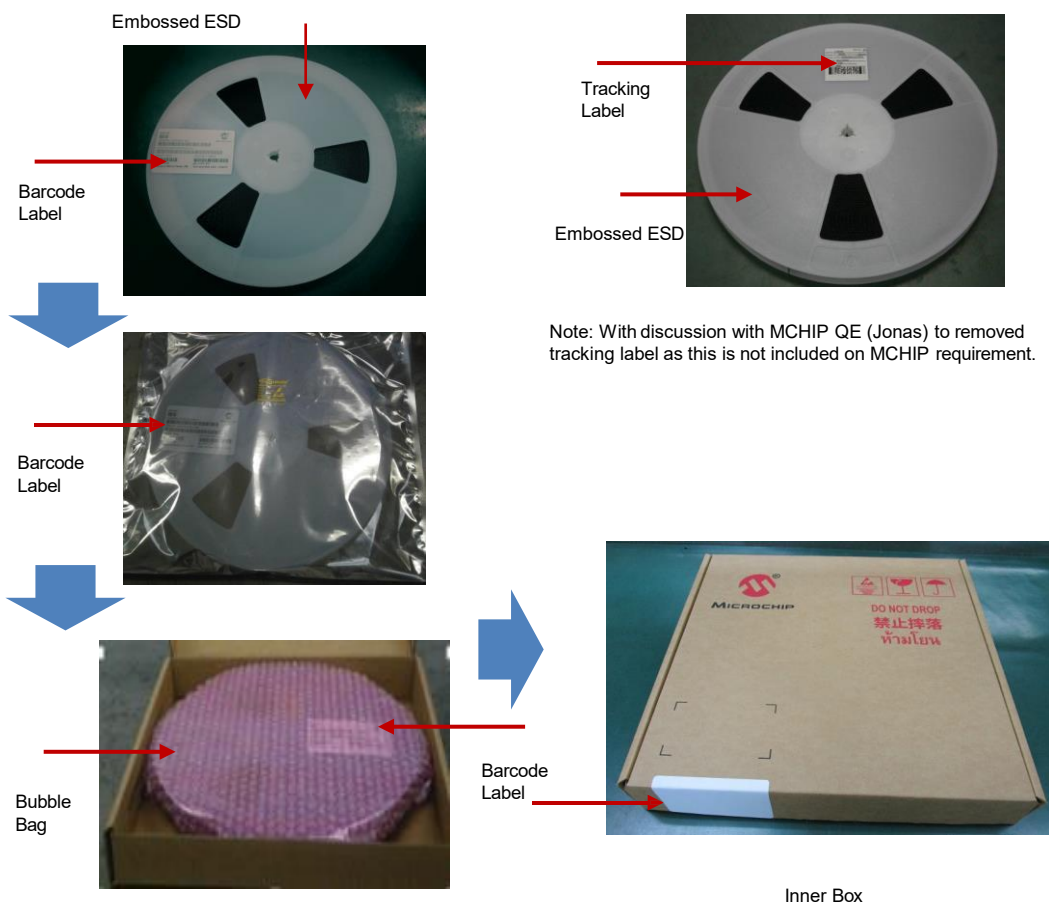
MTAI



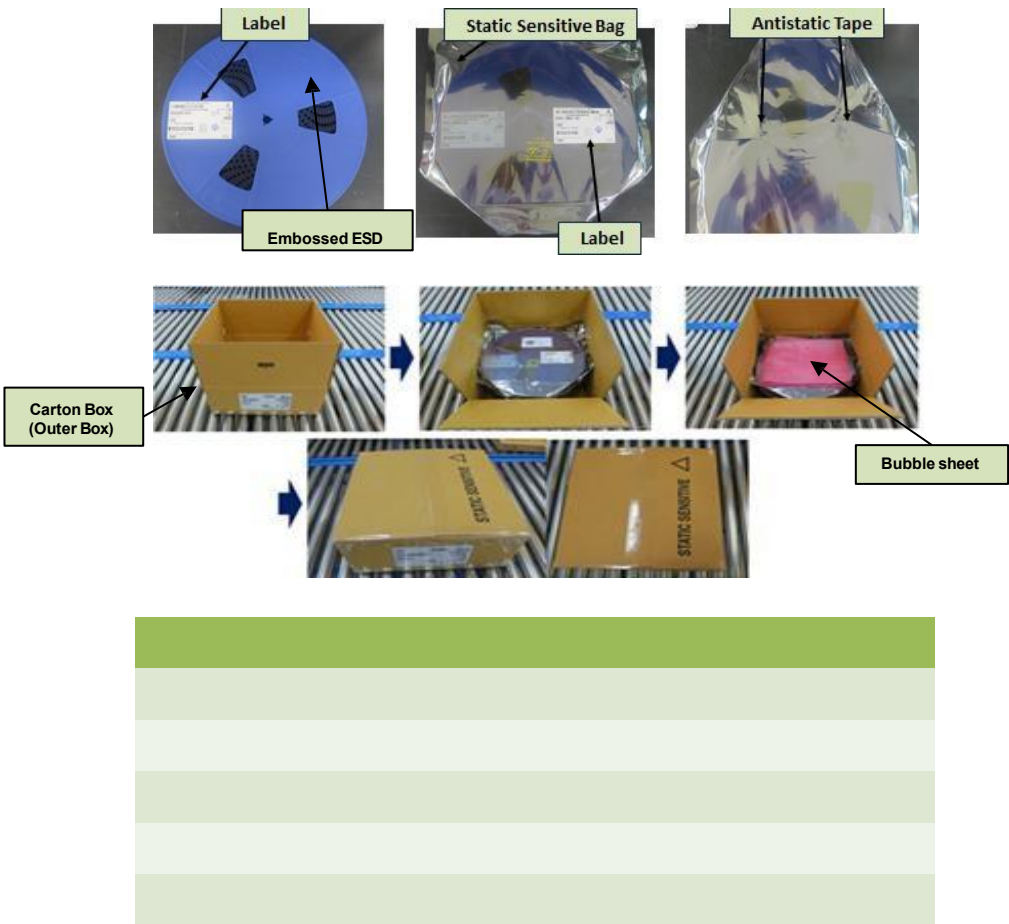
Plant	Reel Diameter (mm)	Reel Hub Size (mm)	W2 MAX (mm)	Color
ANAP	330	100	17.50	White
MTAI	330	100	18.40	Dark Blue

Packing Method Non-Dry Pack

ANAP



MTAI (MSL-1 No inner box)



Eliminating PFAS from Microchip ICs



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

Microchip
August 2025

Eliminating PFAS from MCHP ICs

- **What is PFAS**
- **Microchip's Environmental Stewardship**
- **Microchip Products with PFAS**
- **Time Frame to PFAS-Free Die Attach**
- **What is Die Attach**
- **Will clients be required to switch to PFAS free products**
- **Risk Assessment**

What is PFAS: Poly(Per) FluoroAlkyl Substances (PFAS)

Poly(Per) FluoroAlkyl Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
 - PFAS can be in the product itself.
 - PFAS can also be used to manufacture products while not in the product itself

PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet

Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

Achieving “PFAS-Free” status may serve as a competitive advantage for both Microchip and its clients.

Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

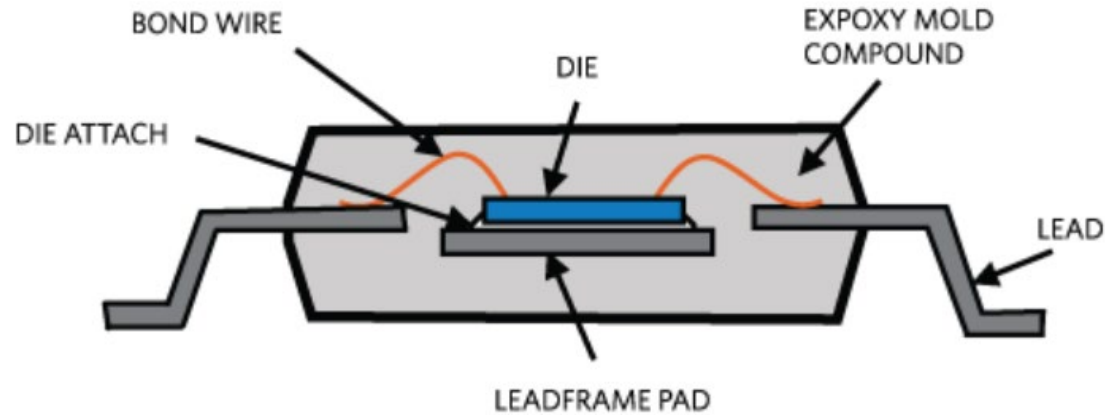
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

What is die attach



A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**

Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.

